#### **MAXIMUM RATINGS**

Symbol		Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage		-0.5 to +7.0	V
V <sub>OUT</sub>	DC Output Voltage		$-0.5$ to $V_{CC} + 0.5$	V
I <sub>IK</sub>	DC Input Diode Current		-20	mA
I <sub>OK</sub>	DC Output Diode Current		± 20	mA
I <sub>OUT</sub>	DC Output Sink Current		± 12.5	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin		± 25	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case	for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+ 150	°C
$\theta_{\sf JA}$	Thermal Resistance	SC70-5/SC-88A (Note 1) TSOP-5	350 230	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	SC70-5/SC-88A TSOP-5	150 200	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	>2000 >200 N/A	٧
I <sub>LATCHUP</sub>	Latchup Performance	Above V <sub>CC</sub> and Below GND at 125°C (Note 5)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	Characteristics		Max	Unit
V <sub>CC</sub>	DC Supply Voltage	2.0	5.5	V
$V_{IN}$	DC Input Voltage	0.0	5.5	V
V <sub>OUT</sub>	DC Output Voltage	0.0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature Range	-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $V_{CC} = V_{CC} = V_{$	3.3 V ± 0.3 V 5.0 V ± 0.5 V 0	100 20	ns/V

#### Device Junction Temperature versus Time to 0.1% Bond Failures

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

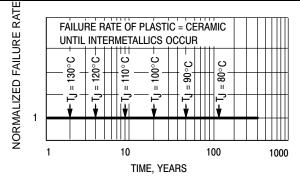


Figure 3. Failure Rate vs. Time Junction Temperature

## DC ELECTRICAL CHARACTERISTICS

			v <sub>cc</sub>	Т	A = 25°	С	T <sub>A</sub> ≤	85°C	−55°C t	o 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage		2.0 3.0 4.5 5.5	1.5 2.1 3.15 3.85			1.5 2.1 3.15 3.85		1.5 2.1 3.15 3.85		V
V <sub>IL</sub>	Maximum Low-Level Input Voltage		2.0 3.0 4.5 5.5			0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65	V
V <sub>OH</sub>	Minimum High-Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -50  \mu\text{A}$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $I_{OH} = -4$ mA $I_{OH} = -8$ mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V <sub>OL</sub>	Maximum Low-Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50  \mu\text{A}$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{IN} = V_{IH}$ or $V_{IL}$ $I_{OL} = 4$ mA $I_{OL} = 8$ mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I <sub>CC</sub>	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1.0		10		40	μΑ

# AC ELECTRICAL CHARACTERISTICS $C_{load}$ = 50 pF, Input $t_{r}$ = $t_{f}$ = 3.0 ns

			Т	T <sub>A</sub> = 25°C		<b>T</b> <sub>A</sub> ≤ 85° <b>C</b>		-55 ≤ T <sub>A</sub> ≤ 125°C		
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Input A or B to Y	$V_{CC} = 3.3 \pm 0.3 \text{ V}$ $C_L = 15 \text{ pF}$ $C_L = 50 \text{ pF}$		4.8 6.1	7.9 11.4		9.5 13.0		11.5 15.5	ns
	Input A of B to 1	$V_{CC} = 5.0 \pm 0.5 \text{ V}$ $C_L = 15 \text{ pF}$ $C_L = 50 \text{ pF}$		3.7 4.4	5.5 7.5		6.5 8.5		8.0 10.0	
C <sub>IN</sub>	Maximum Input Capacitance			5.5	10		10		10	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
$C_{PD}$	Power Dissipation Capacitance (Note 6)	11	pF

<sup>6.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

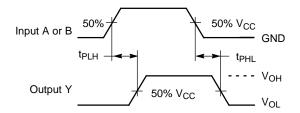
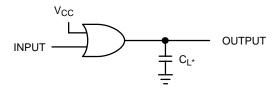


Figure 4. Switching Waveforms



\*Includes all probe and jig capacitance. A 1–MHz square input wave is recommended for propagation delay tests.

Figure 5. Test Circuit

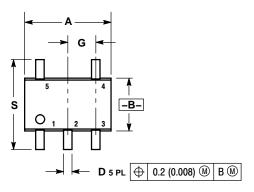
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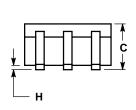
Device	Package	Shipping <sup>†</sup>
MC74VHC1G32DFT1	SC70-5/SC-88A/SOT-353	
MC74VHC1G32DFT1G	SC70-5/SC-88A/SOT-353 (Pb-Free)	
MC74VHC1G32DFT2	SC70-5/SC-88A/SOT-353	
MC74VHC1G32DFT2G	SC70-5/SC-88A/SOT-353 (Pb-Free)	3000 / Tape & Reel
MC74VHC1G32DTT1	SOT23-5/TSOP-5/SC59-5	
MC74VHC1G32DTT1G	SOT23-5/TSOP-5/SC59-5 (Pb-Free)	

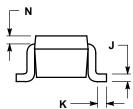
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **PACKAGE DIMENSIONS**

SC-88A, SOT-353, SC-70 CASE 419A-02 **ISSUE J** 







- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

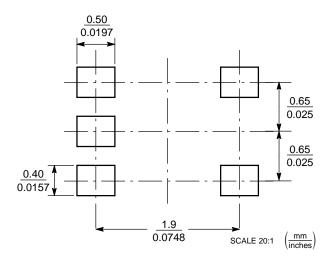
  2. CONTROLLING DIMENSION: INCH.

  3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

  4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65 BSC	
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20	REF
S	0.079	0.087	2.00	2.20

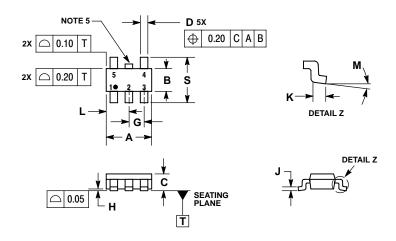
## **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

TSOP-5 CASE 483-02 ISSUE F

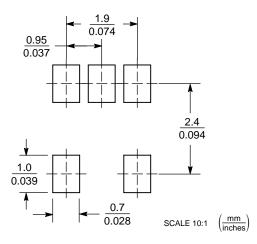


- NOTES:

  1. DIMENSIONING AND TOLERANCING PER
  ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. MAXIMUM LEAD THICKNESS INCLUDES
- LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  DIMENSIONS A AND B DO NOT INCLUDE
- MOLD FLASH, PROTRUSIONS, OR GATE BURRS
- OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

	MILLIMETERS					
DIM	MIN	MAX				
Α	3.00	BSC				
В	1.50	BSC				
C	0.90	1.10				
D	0.25	0.50				
G	0.95	BSC				
Н	0.01	0.10				
7	0.10	0.26				
K	0.20	0.60				
L	1.25	1.55				
М	0 °	10°				
S	2.50	3.00				

#### SOLDERING FOOTPRINT\*



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